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* Beware of counterfeit products.
Counterfeit SMIC solder products of various kinds have been circulating abroad.
Always purchase genuine SMIC products from SMIC subsidiaries or authorized distributors.

SMIC SOLDERING MATERIALS CATALOGUE



Continuously Developing Soldering Materials To Create a Sustainable Society

In 2000, Senju Metal Industry commercialized M705, a standard alloy for lead-free solder. It has played a major role in making electronic components and devices lead-free. Today, there is a strong demand to minimize solder joints, improve joint reliability in strained environments for on-board electrical components, and support carbon neutrality. Senju Metal Industry has focused on the development of soldering materials suitable for various needs, expanded its product lineup, and is continuing to contribute to improving the reliability of electronic devices through continuous verification, assuming the operating environments of semiconductors, industrial equipment, and on-board electrical components. Senju Metal Industry will continue to further develop soldering materials and pioneer the future of the global environment and connections.

We are pioneering the future of joints and connections with a "Total Solution" by providing various forms of soldering materials.



SOLDER ALLOY P3

All the solder alloy products are eco-friendly and in harmony with the global environment. We offer an extensive product lineup, allowing our clients to choose the product that best suits their purpose and application.



SOLDER PASTE P5

A product made by mixing fine solder powder and high-viscosity flux to form a paste. This is an essential material for surface mounting.



FLUX CORED P7

This product contains flux in the center of a coil of solder. It is widely used in construction methods that use soldering irons.



POST FLUX P8

A liquid flux product for use with flux-free solder materials. It improves solderability.



SOLDER PREFORM ... P9

Solder worked into various structures and shapes. It has been used in recent years for power semiconductor packaging in xEVs.



SOLDER BALL P11

A spherical product used for semiconductor bumping. We can also manufacture micro balls with a diameter of 100 μm or less.



FLUX for SEMI-CONDUCTORS ... P13

This is a highly viscous flux product mainly used with solder balls. It provides excellent ball retention and solderability.



MILATERA P15

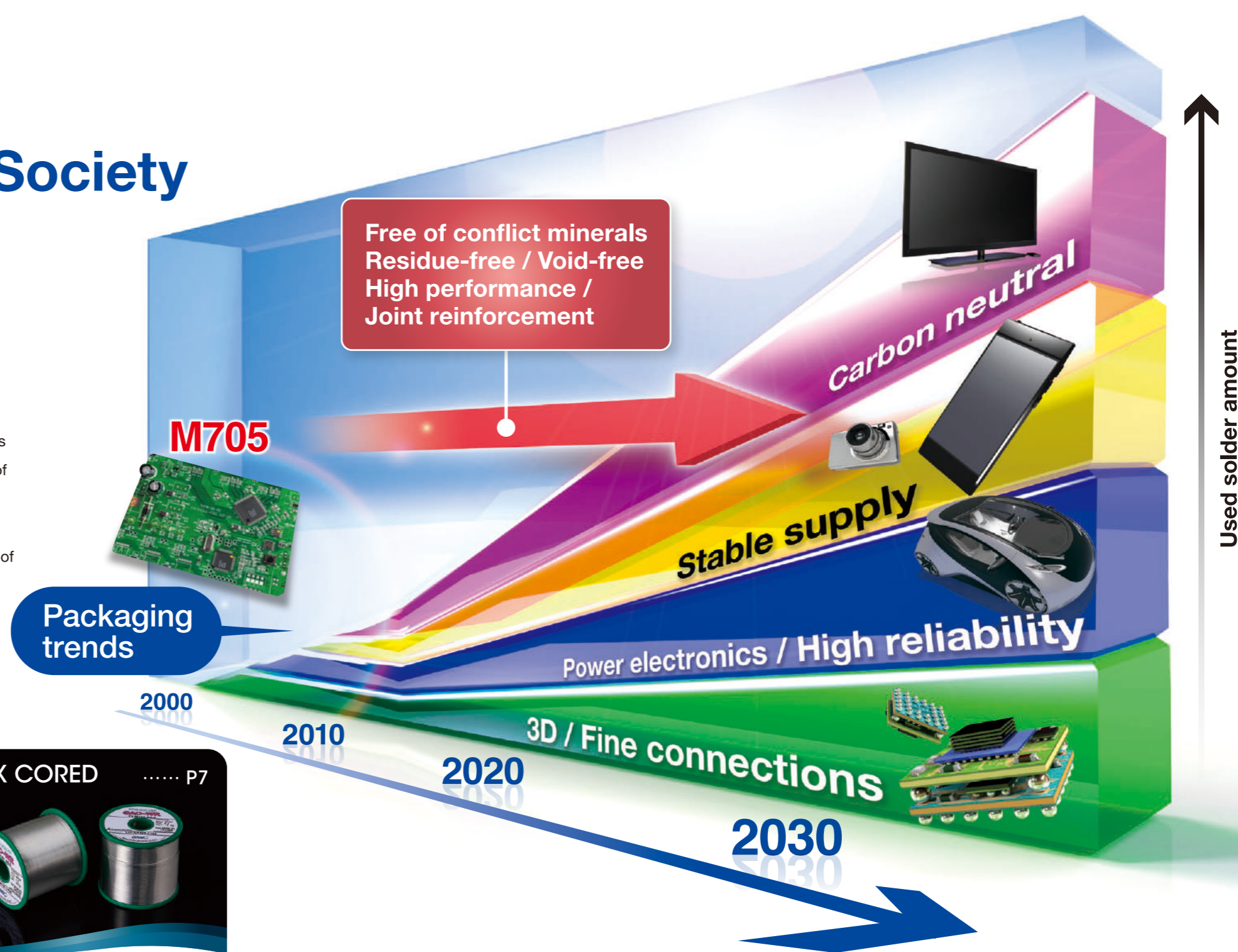
MILATERA
Low Temperature Soldering for Earth

A unique low-temperature soldering solution that integrates materials, equipment, and methods. It contributes to carbon neutrality.



Recycling and Environmental Support ... P20

We will contribute to building a sustainable society by working towards a zero-emission society through our business activities.



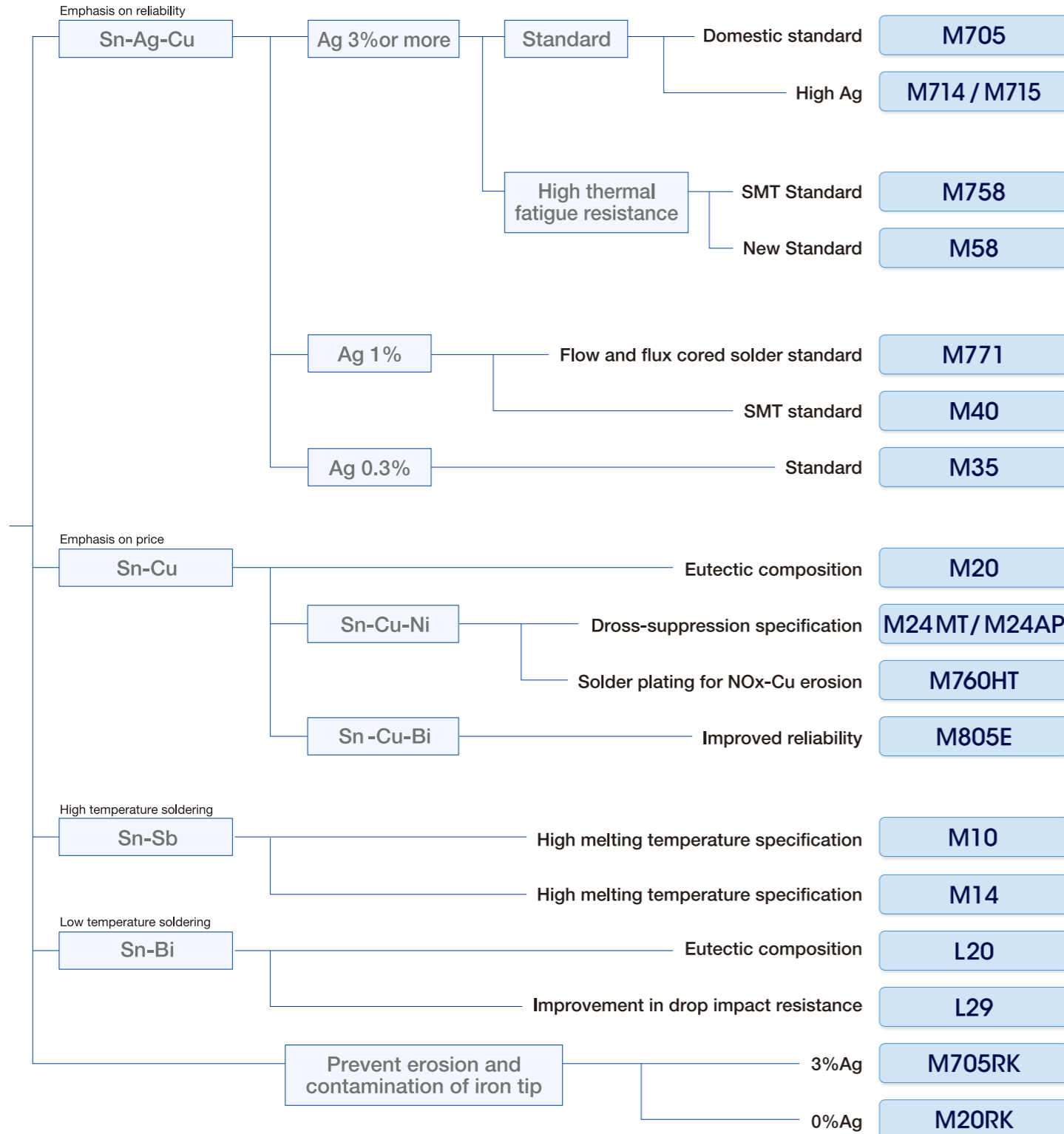
SOLDER ALLOY

The core soldering technology to meet a variety of requirements.



All our products are eco-friendly and can be selected according to purpose and application.

We offer an extensive product lineup for customers to choose from according to their requirements.



Alloy List

	Alloy composition (wt%)	Melting temperature (°C)			Form					Overview
		Solidus line	Peak	Liquidus line	BAR	PASTE	FLUX CORED	PREFORM	BALL	
ECOSOLDER										
M705	Sn-3.0Ag-0.5Cu	217	219	220	●	●	●	●	●	Pb-free general-purpose solder alloys
M31	Sn-3.5Ag-0.75Cu	217	219	219	●	●	●	●	●	
M714	Sn-3.8Ag-0.7Cu	217	219	220	●	●	●	●	●	
M715	Sn-3.9Ag-0.6Cu	217	219	226	●	●	●	●	●	
M710	Sn-4.0Ag-0.5Cu	217	219	229	●	●	●	●	●	
M771	Sn-1.0Ag-0.7Cu	217	219	224	●	●	●	●	●	Low Ag/No Ag solder alloys
M35	Sn-0.3Ag-0.7Cu	217	219	227	●	●	●	●	●	
M20	Sn-0.75Cu	227	229	229	●	●	●	●	●	
M24MT	Sn-0.7Cu-Ni-P-Ge	228	230	230	●	●	●	●	●	
M24AP	Sn-0.6Cu-Ni-P-Ge	227	228	228	●	●	●	●	●	
M805E	Sn-0.3Bi-0.7Cu-P	225	229	229	●	●	●	●	●	High reliability solder alloys
M40	Sn-1.0Ag-0.7Cu-Bi-In	211	222	222		●	●	●	●	
M814	Sn-3.4Ag-0.7Cu-Bi-Sb-Ni-Co	201	222	222	●	●	●	●	●	
M58	Sn-3.4Ag-0.7Cu-Bi-Sb-Fe-Co	210	221	221	●	●	●	●	●	
M731	Sn-3.9Ag-0.6Cu-3.0Sb	221	224	226	●	●	●	●	●	
M716	Sn-3.5Ag-0.5Bi-8.0In	196	208	214		●	●	●		Solder alloys for power semiconductors
M725	Sn-0.7Cu-Ni-P	228	230	230	●	●	●	●	●	
M10	Sn-5.0Sb	240	243	243	●	●	●	●	●	
M14	Sn-10Sb	245	248	266	●	●	●	●	●	
M754	Sn-0.6Cu-7Sb	235	239	242	●	●	●	●	●	
M709	Sn-0.5Ag-6.0Cu	217	226	378	●					Solder alloys for terminal processing
M760HT	Sn-5.0Cu-0.15Ni-P-Ga	228	229	365	●					
M770	Sn-2.0Ag-Cu-Ni	218	220	224	●	●	●	●	●	Highly reliable solder alloys for semiconductor PKG
M850	Sn-3.5Ag-0.8Cu-Bi-Ni-Co-Ge	217	221	221	●	●	●	●	●	
M758	Sn-3.0Ag-0.8Cu-Bi-Ni	205	215	215		●	●	●	●	
M832	Sn-3.5Ag-0.8Cu-Bi-Ni	203	214	214		●	●	●	●	
M807	Sn-3.5Ag-0.8Cu-Bi-Ni	214	219	219		●	●	●	●	
M705RK	Sn-3.0Ag-0.5Cu-Fe-Zr	219	221	221			●			Flux cored solder alloys to prevent iron tip corrosion
M20RK	Sn-0.75Cu-Fe-Zr	227	229	229			●			
M35RK	Sn-0.3Ag-0.7Cu-Fe-Zr	217	219	227			●			
MILATERA										
L20	Sn-58Bi	139	141	141	●	●	●	●	●	Low temperature solder alloys
L23	Sn-57Bi-1Ag	138	140	204	●	●				
L27	Sn-40Bi-Cu-Ni	139	140	174		●				
L28	Sn-35Bi-Cu-Ni	141	143	182		●				
L29	Sn-58Bi-Sb-Ni	140	145	145		●				

Peak temperature: Endothermic peak on a DSC (Differential Scanning Calorimetry) curve
 Some alloy compositions may not be available in certain forms with special product size and grade.
 For inquiries regarding alloy compositions not listed, contact our sales representative or visit our website (<https://www.senju.com/>).

Lead-free product impurity standard (unit: percentage by mass)

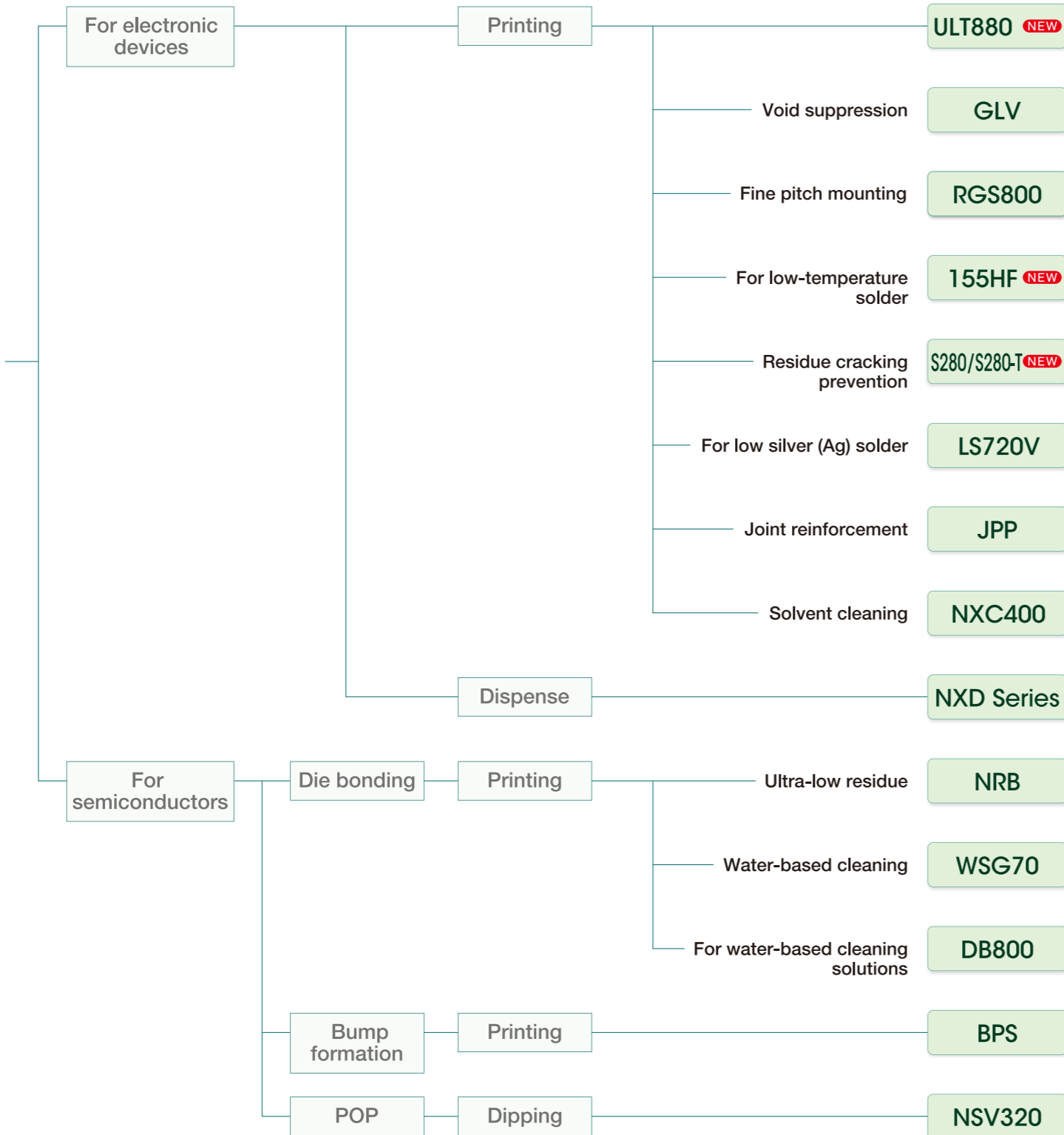
Sb	Cu	Bi	Zn	Fe	Al	As	Cd	Ag	In	Ni	Au	Pb
0.07 or less	0.05 or less	0.05 or less	0.001 or less	0.02 or less	0.001 or less	0.03 or less	Less than 0.002	0.03 or less	0.02 or less	0.01 or less	0.005 or less	Less than 0.05

SOLDER PASTE

Solder paste is a product made by mixing fine solder alloy powder and flux components

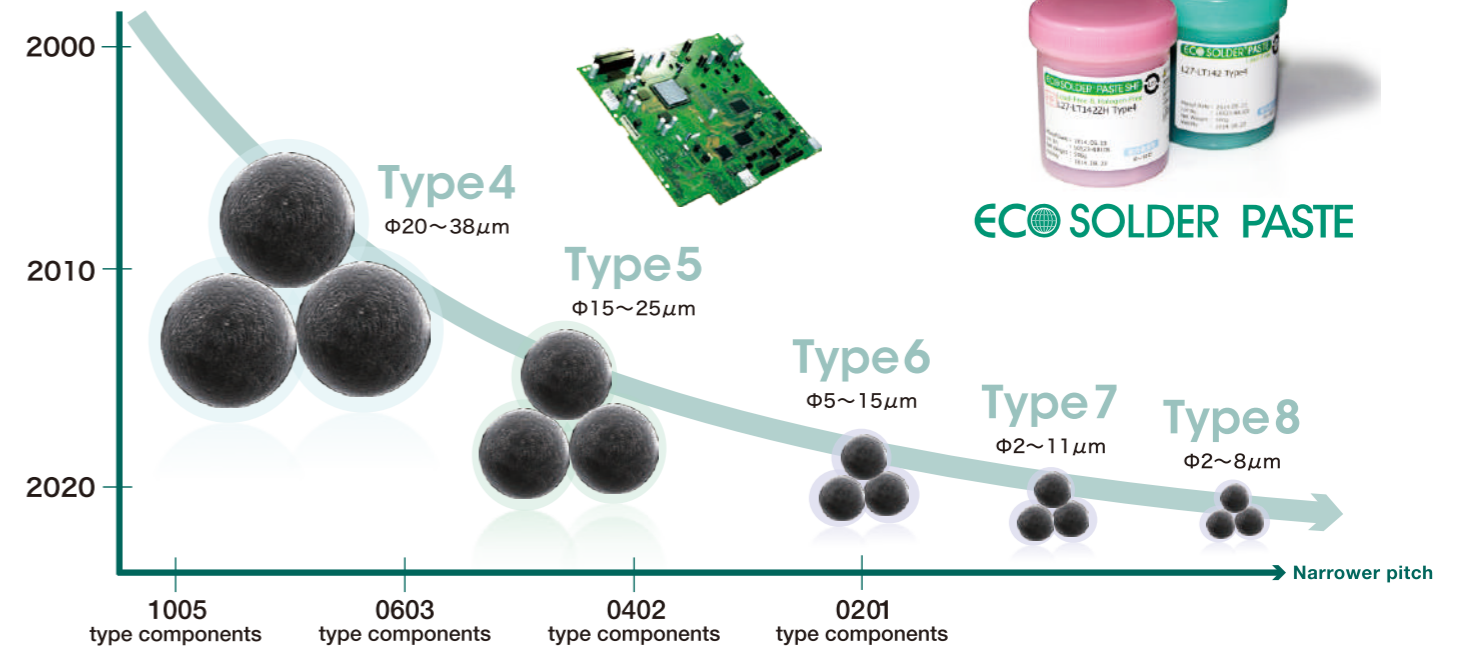


Select the best solder paste for your purpose and application in the development of next-generation products

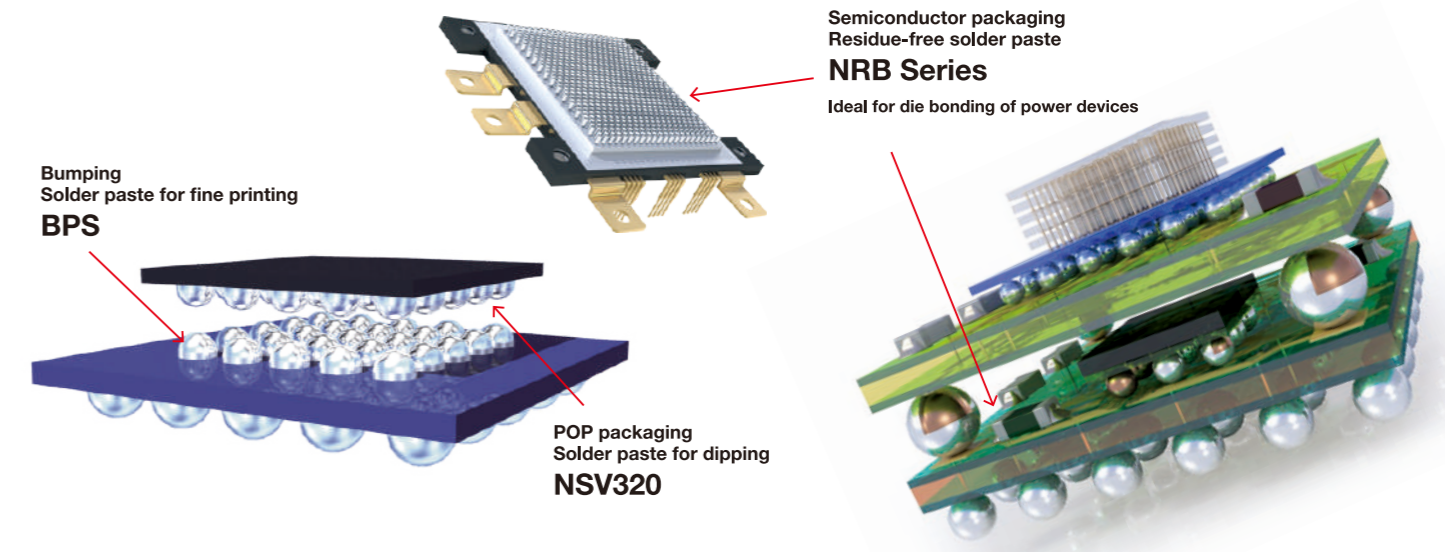


Development of new fluxes for finer powders

The finer the powder, the greater the surface area and the greater the amount of oxidation, requiring high-activity fluxes that suppress re-oxidation during reflow.



Solder paste for semiconductor packaging



Packing example

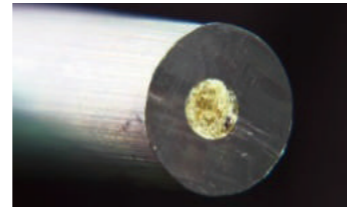


FLUX CORED

Flux-cored solder is a wire solder that has flux in the center of the wire



- We are continuing to develop a diverse product lineup of flux-cored solders. Select the type that best suits your purpose and application



Type	Feature	FLUX	Flux Type IPC J-STD-004C	Adaptation method			
				Soldering	Robot	Laser heating	Sleeve heating
High workability	Emphasis on wetting speed	GAO-WR	ROL1	○	○	○	—
	Emphasis on finish	GAO-ST	ROM1	○	○	—	—
	Low fumes	GAO-LF	ROM1	○	○	—	○
	For low-temperature soldering	LEO-2	ROL1	○	○	—	—
High reliability	Standard	SEN	ROL1	○	○	○	○
	Residue cracking suppression	MACROS	ROL1	○	○	○	—
	Halogen free	HAL	ROL0	○	○	○	○
	Low temperature soldering / Halogen free	LEO-2-HF	ROL0	○	○	—	—

Road map to lead-free and flux-cored solder

● Workability enhancement (anti-wetting measures)



● Reliability enhancement (measures for insulation properties)



● Soft residue (migration prevention)



● Halogen-free



● Shift to low temperature soldering



Packing example

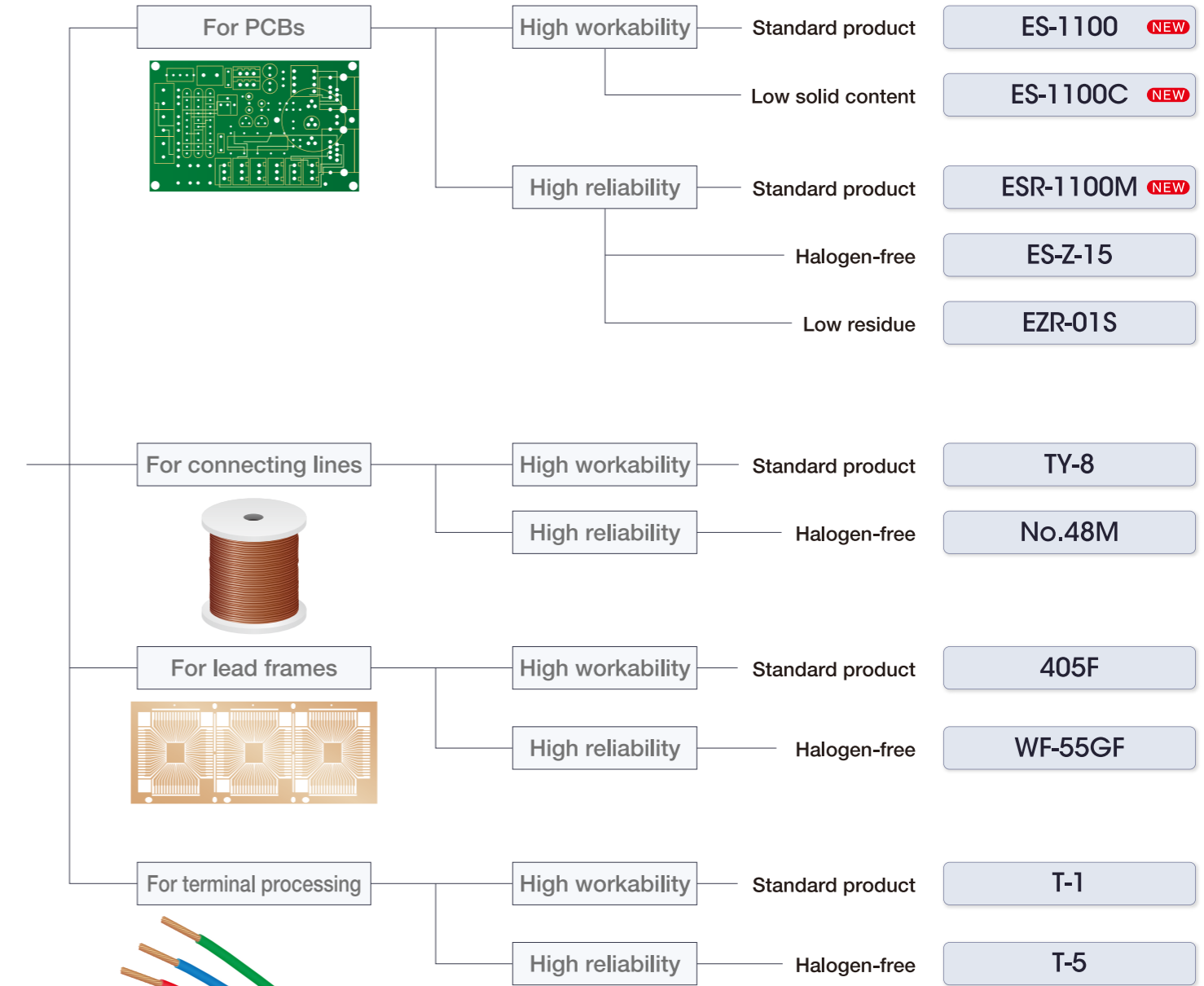


POST FLUX

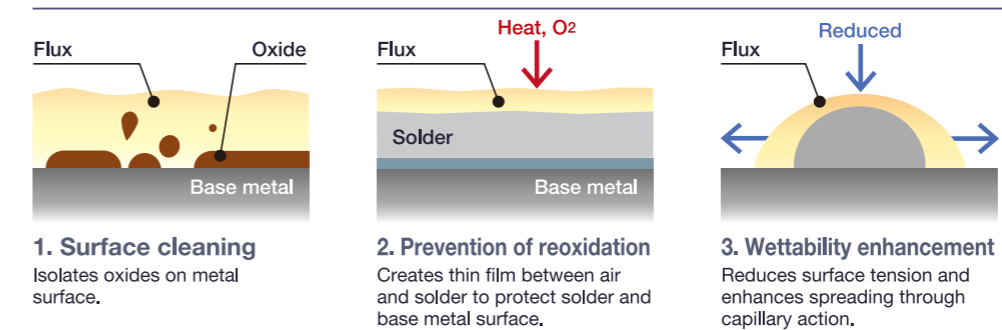
Post flux is a liquid mixture of rosin and other resins with activators and solvents



- Select the most effective product for soldering based on your application and purpose



Functions of flux



Packing example



SOLDER PREFORM

Solder alloys worked into various shapes to achieve effective soldering

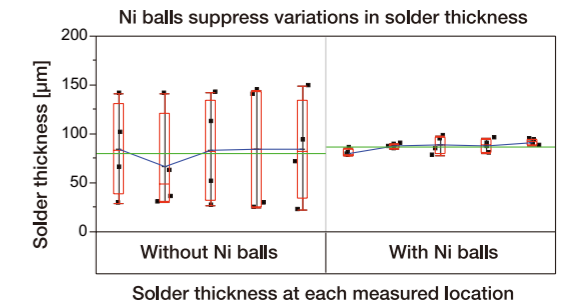
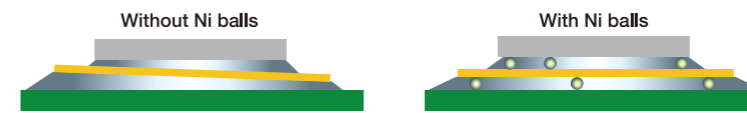
Supporting the future of solder packaging with a diverse product lineup

In addition to solder alloy composition, shape, and dimensions, each of the five processing shapes can be selected to achieve a variety of synergies with Solder Preform.

	Single Layered	Ni Balls Contained	Flux Cored	Shape
Ribbon				<p>W Width Min = 0.5mm Max = 70mm</p> <p>L Length Please ask about this specification.</p> <p>T Thickness Min = 0.05mm Max = 0.35mm</p>
Square				<p>SIDE A Min = 0.5mm Max = 100mm</p> <p>SIDE B Min = 0.5mm Max = 70mm</p> <p>T Thickness Min = 0.05mm Max = 2.5mm</p>
Disc				<p>OD Outer Diameter Min = 0.3mm Max = 62mm</p> <p>T Thickness Min = 0.05mm Max = 2.5mm</p>
Washer				<p>OD Outer Diameter Min = 1.2mm Max = 40mm</p> <p>ID Inner Diameter Min = 0.6mm Max = 35mm</p> <p>W Width Min = 0.05mm Max = 2.5mm</p> <p>Processing condition: $(OD-ID) \div 2 \geq T$</p>
Chip				<p>SIDE A Min = 0.6mm Max = 3.2mm</p> <p>SIDE B Min = 0.3mm Max = 1.6mm</p> <p>T Thickness Min = 0.3mm Max = 1.6mm</p>

*Min. and Max. processing dimensions depend on alloy composition and type. Contact our sales department for details.

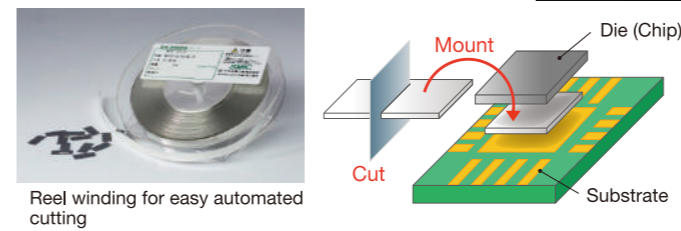
Effect of pellets containing Ni balls



Applying shape characteristics to packaging applications

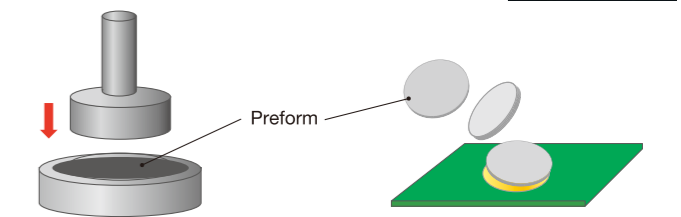
Ribbon

A tape-like preform wound on a reel can be cut into desired shapes just before mounting



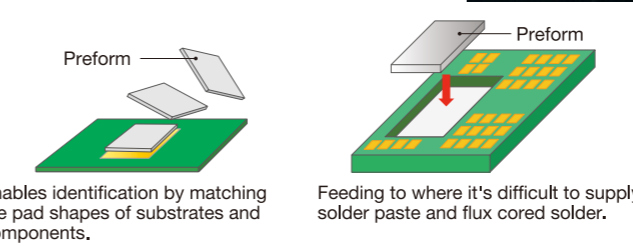
Disk

Supplies the solder alloy of the same shape as that of the soldering location



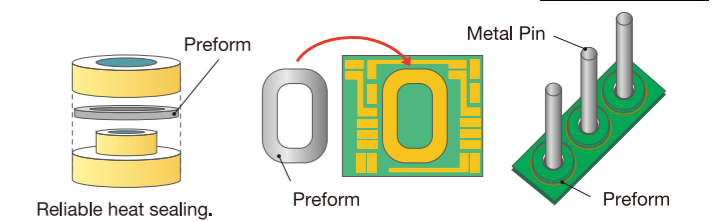
Square

Supplies the soldering location with a fixed amount of solder within a given tolerance range



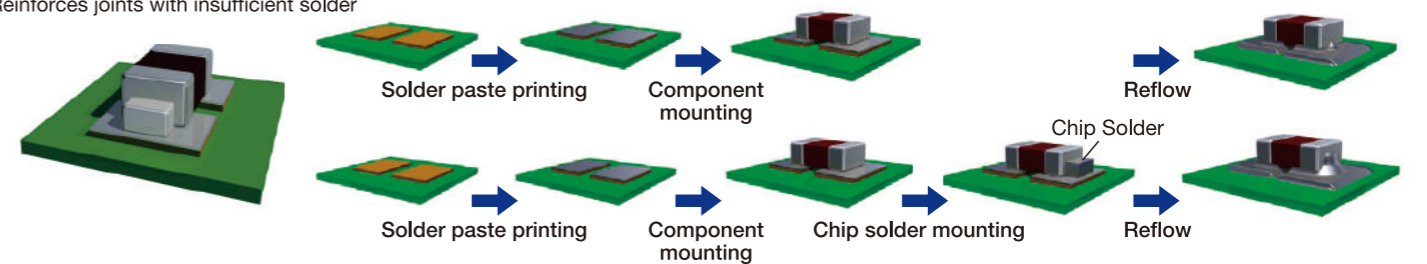
Washer

Ensures reliable heating and melting of difficult-to-print paste areas and prevents uneven heating

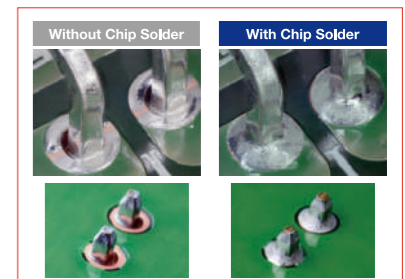
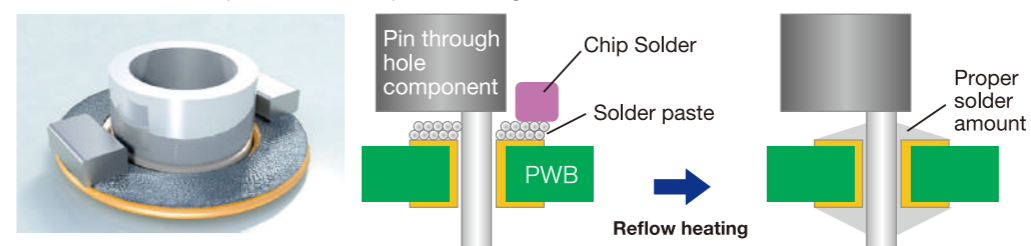


Chip

Automatic mounting is possible with chip mounters
Reinforces joints with insufficient solder



Joint reinforcement of pin thru-hole components using reflow



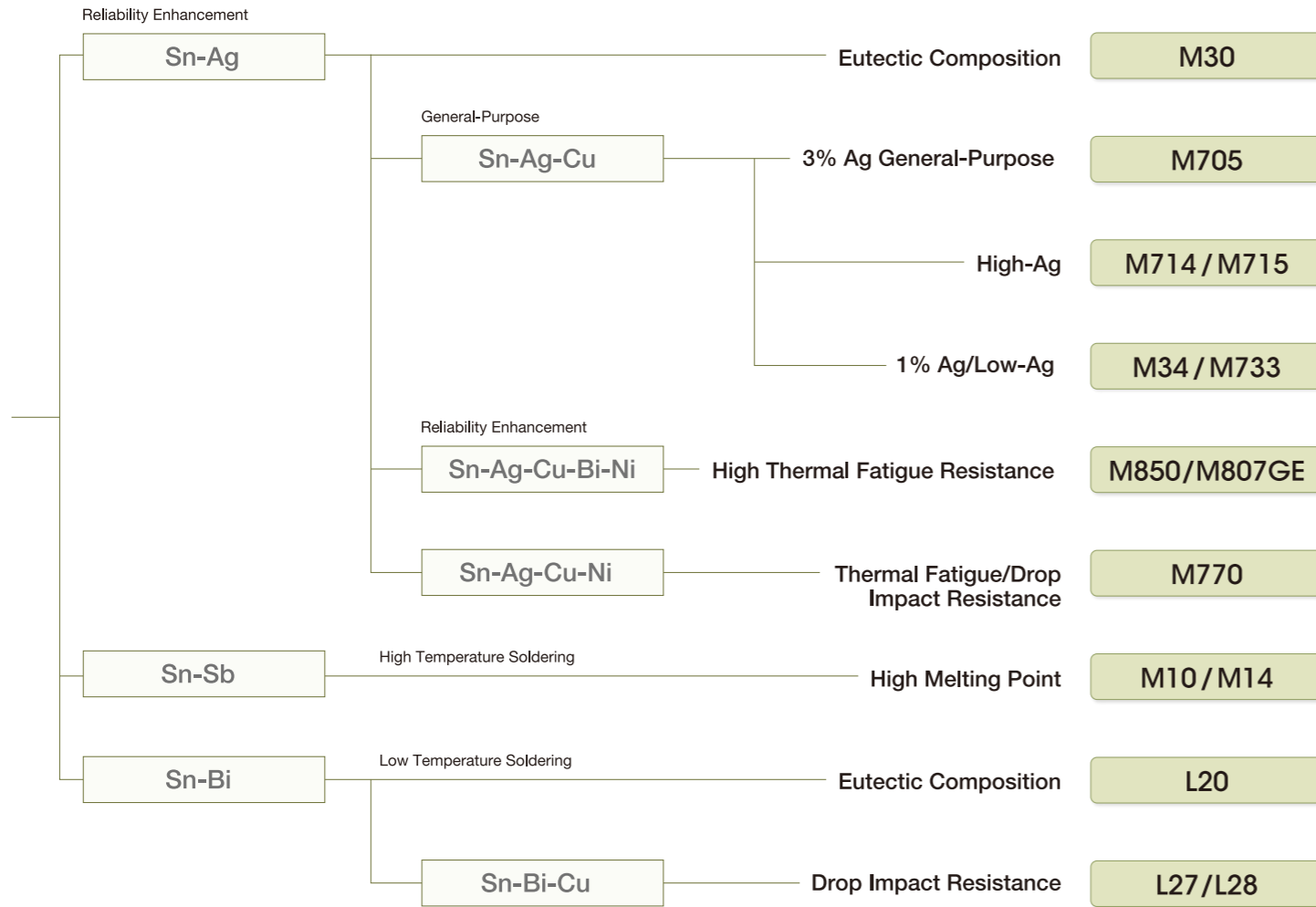
Note) Various shapes and sizes can be made according to customer requirements.

SOLDER BALL

Solder balls are highly spherical balls with guaranteed dimensions and tolerances



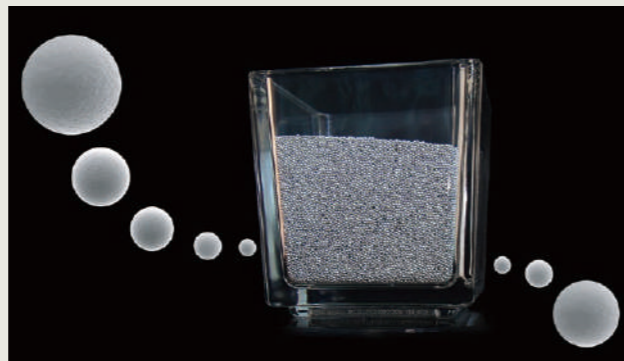
Various compositions and ball diameters are available to support state-of-the-art semiconductor packaging



LAS Solder Ball protects Products from "Soft Errors"

Trace amount of alpha rays or cosmic rays discharged from solder materials or semiconductor materials may rewrite memory data, which is called "soft error." In particular, flip chip package is highly sensitive to soft errors, and reduction of alpha rays is required for solder materials or other electronic packaging materials. LAS solder ball is material meets this requirement.

- Standard specification product
- Diameter : 40 to 120 μm
- Alpha count : 0.002 cph/cm² or less
- Composition : M705 M200

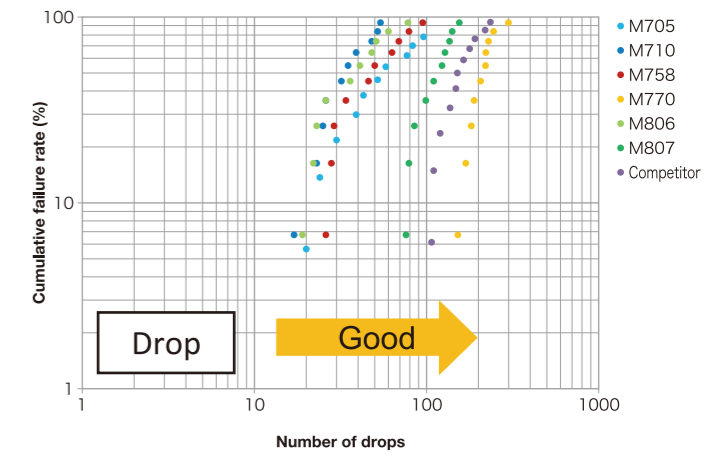
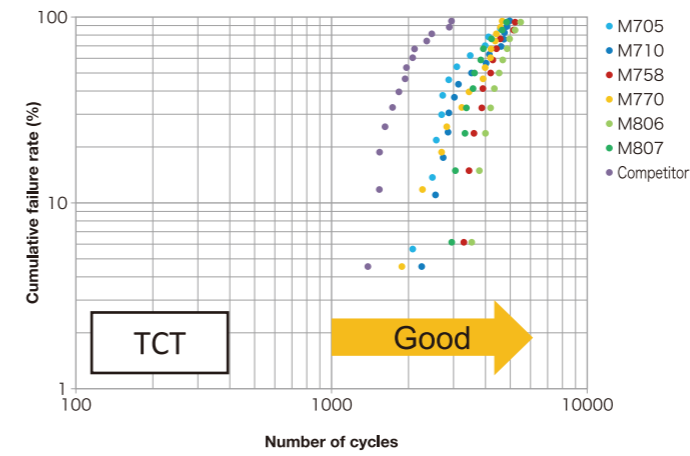


TCT and drop test with CSP

CSP
Size : 12 x 12 mm
SRO : 0.24mm
Pitch : 0.5mm
Ball : 0.3mm
S/F : Cu

TEST Condition
[TCT]
Temperature Cycle : -40°C/+125°C each 10min

[Drop]
Impact acceleration : 1500G/Half-sine pulse 0.5msec.

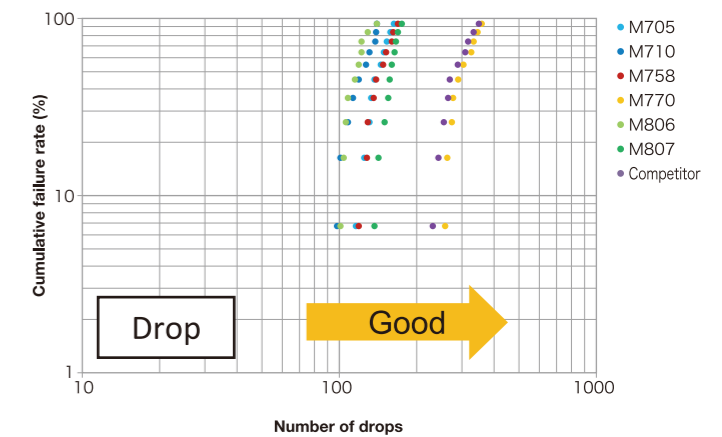
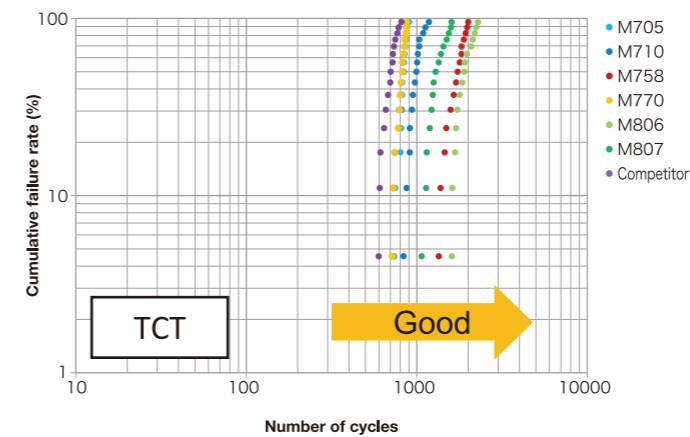


TCT and drop test with WLP

WLP
Size : 7 x 7 mm
SRO : 0.24mm
Pitch : 0.5mm
Ball : 0.3mm
S/F : Cu

TEST Condition
[TCT]
Temperature Cycle : -40°C/+125°C each 10min

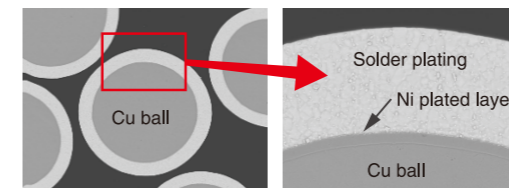
[Drop]
Impact acceleration : 1500G/Half-sine pulse 0.5msec.



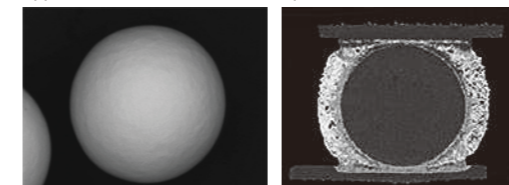
Cu Cored Ball

Advanced plating technology easily secures space in 3D soldering

Cross-sectional photos

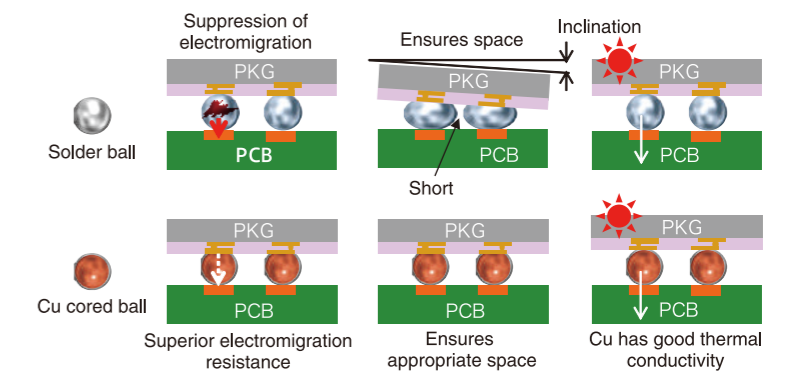


Appearance and cross-sectional photos of M90

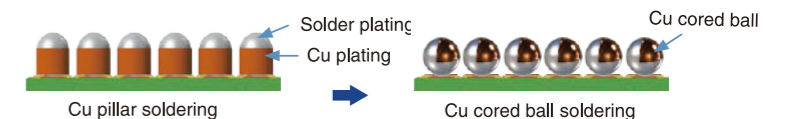


M90 improves drop impact resistance through reforming of the joint interface by Ni in the Ni plating.

Features



Example of Cu cored ball (substituting Cu pillar)



FLUX for SEMI-CONDUCTORS

Semiconductor flux is a liquid mixture of rosin or other resins, with activators, and solvents



Select the most effective product for soldering based on your application and purpose

Flux for Packaging

Application	Type	Heating	Process	Product		
Chip Attach	Water Soluble	Reflow/TCB	Transfer	WF-6317/WF-6450HA		
			Print	WF-6317P/WF-6458		
			Spray	WF-6450SP(LS)-1		
	Rosin Type	Reflow	Transfer	GTN-68/GTN-68(HF)		
			Print	GTN-68P/GTN-68P(HF)		
			Low Residue	Reflow	Transfer	901K5
					Spray	LR-9001T1SP
	TCB	Transfer/Spray		NRF-SP1		
			Ball Attach	Water Soluble	Reflow	Transfer
	Print	WF-6317P/WF-6458				
Rosin Type	Reflow	Transfer				GTN-68/GTN-68(HF)
		Print		GTN-68P/GTN-68P(HF)		

Flux for Micro Bump Formation

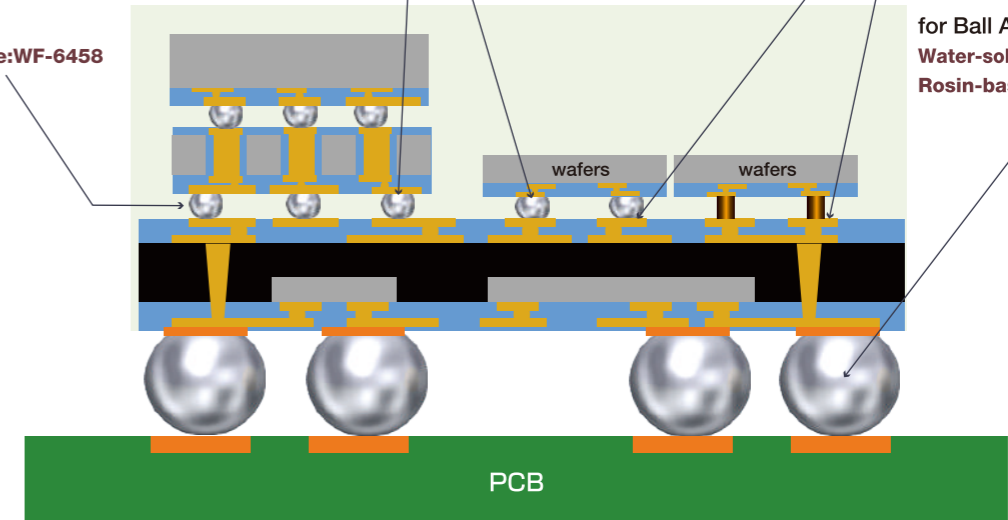
Application	Type	Heating	Process	Product
Micro Ball Attach	Water Soluble	Reflow	Print	WF-6458
	Rosin Type	Reflow	Print	MB-T100/MB-T200
Fusing	Water Soluble	Reflow	Spray/Spincoat	SPK-3420
	Rosin Type	Reflow	Spray/Spincoat	7200A

for Micro Bump
Water-soluble:WF-6458
Rosin-based:MB-T100/MB-T200

for Chip Attach (Flip Chip)
Water-clean:WF-6317,WF-6450HA
Rosin-based:GTN-68
Ultra-low residue:901K5

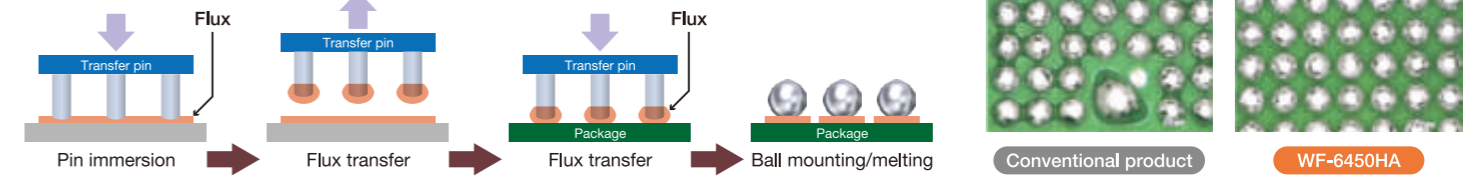
for Flushing
Water-soluble:WF-6458

for Ball Attach (BGA)
Water-soluble:WF-6317,WF-6450HA
Rosin-based:GTN-68



WF-6450HA

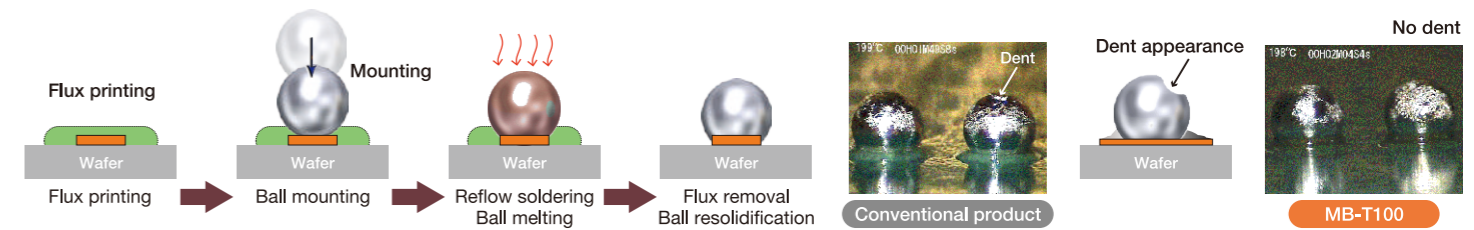
Suppresses bridge even at ball attachment to narrow-pitched package



MB-T100

Highly-activated MB-T100 reproduces dent-free spheres when balls are resolidified

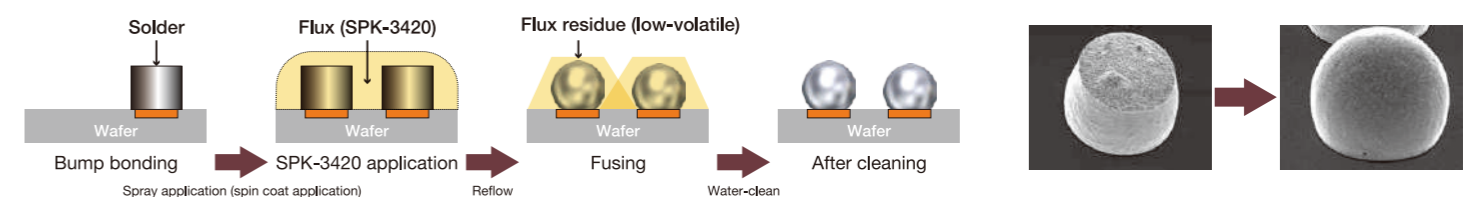
Highly-activated and exhibits high heat resistance, and can be cleaned with semi-aqueous cleaning solution. A halogen-free product is also available.



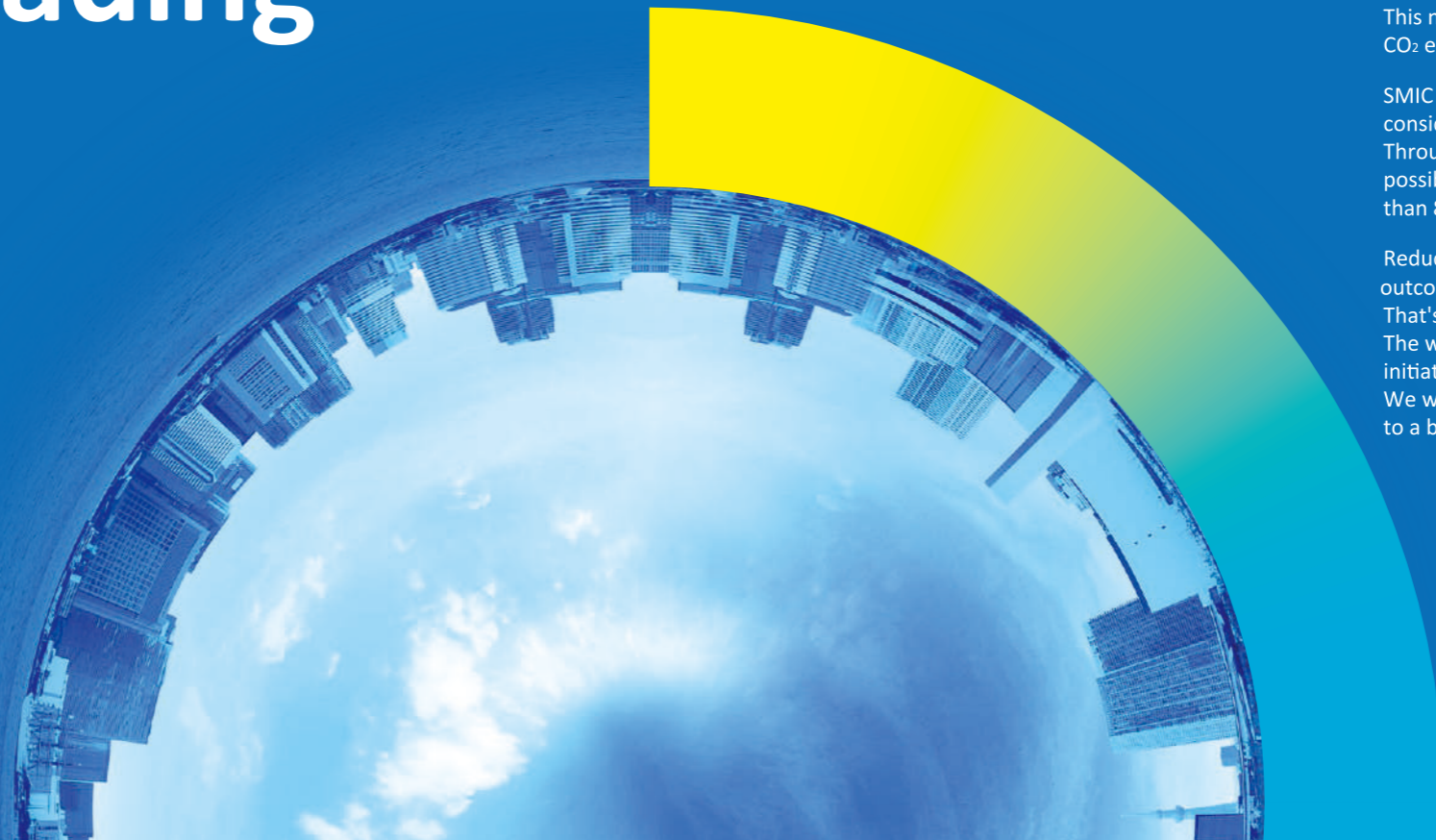
SPK-3420

SPK-3420 forms even spherical bumps, and flux residue can be removed by water-cleaning

Halogen-free flux that can be easily removed by water-cleaning even after high-temperature reflow soldering.



To a future leading to $\Delta t 80^{\circ}\text{C}$



Soldering requirements have changed with the times, and SMIC's low-temperature soldering solution "MILATERA" is the answer.

We provide "MILATERA" to the customers in a three-part system which includes materials, equipment, and our soldering method. Solders with a melting point about 80°C lower than conventional solders allows for low-temperature mounting. This new carbon-neutral option reduces significant burdens, costs, and CO_2 emissions throughout the supply chain.

SMIC is aiming for a future where manufacturing is done while considering both people and the environment. Through our technology and passion, we will pave the way for various possibilities as partners in ushering in a bright future nurtured over more than 80 years.

Reducing temperature can reduce other factors and lead to positive outcomes. That's why the reduction by SMIC's "MILATERA" will lead to a positive future. The warmheartedness of our customers and partners who support this initiative will help to lower the earth's temperature. We want to deliver next-generation mounting technologies that will lead to a brighter future for both companies and society.

Wave soldering



BITHUS-Wave
MTF-300



Flux mixing machine
MTM-4L



TABLUX



MILATERA BAR



MILATERA PASTE



MILATERA FLUX CORED

Reflow soldering

Manual soldering

NEW BITHUS-Wave MTF series

Adapted to the challenges of low-temperature wave soldering



[Features]

- Newly developed proprietary mechanism adapted to low-temperature soldering
- Possible reduction of CO₂ emissions during production by 15% or more
- Confirmed high joint reliability and sufficient shock resistance after soldering

BITHUS-Wave
MTF-300



RK Nozzle that inhibits dross adhesion for superior solderability

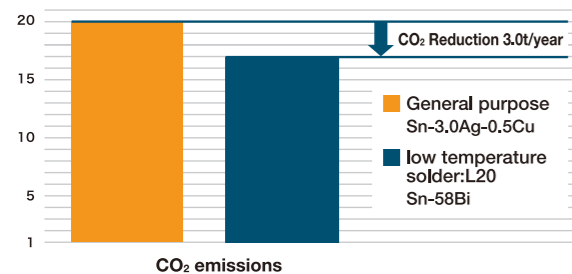


Air Curtain Quenching System for reliable solder solidification



SY Cutter that enables dross reuse

CO₂ reduction calculation



Solder type	General purpose Sn-3.0Ag-0.5Cu	low temperature solder:L20 Sn-58Bi	Reduction amount	unit	Reduction rate
Electric energy	57,024	48,384	▲8,640	kWh/year	-15.15%
CO ₂ emissions	20.01	16.98	▲3.0	t/year	-15.14%

Calculation method
Assuming 8,640 hours/year of operation at the standard temperature setting for each solder for one of our wave soldering machines

High joint reliability

No cracks leading to breakage

PCB	Consumer-use PCBs
Observation target	Power relay components
Test conditions	After 2,000 cycles or more at -50/85°C, 30 min each

No breakage even after 100 drops at 1,500 G

Test method: Drop, impact force

Fillet surface Fillet cross section

	MTF-300	MTF-400
Dimensions (LxWxH)	4,340 x 1,340 x 1,540 mm	4,340 x 1,340 x 1,540 mm
Conveyor height	780±20 mm	780±20 mm
Conveyor Speed	0.5 - 2.0 m/min	0.5 - 2.0 m/min
PCB dimensions (WxL)	50 x 100 - 300 x 450 mm	50 x 100 - 400 x 450 mm
Component height(highest)	≤100mm, ≥5mm	≤100mm, ≥5mm
Preheater (heated zone length)	1,600 (400/zonex4) mm	1,600 (400/zonex4) mm
Solder pot capacity (approx.)	460kg(L20,Sn-58Bi)	460kg(L20,Sn-58Bi)
Power requirement	200V, approx.32.5kW, 100A, 3-phase	200V, approx.32.5kW, 100A, 3-phase

NEW Flux mixing machine MTM-4L·TABLUX

Streamlining Flux Transportation and Storage and Contributing to Carbon Neutrality



Flux mixing machine
MTM-4L

[Features]

- Solidified flux can be handled as a non-hazardous material
- Easy to produce the required amount of flux at the customer's site
- Solvents are procured through customer-accessible sources



Resin-based solid flux
TABLUX

	MTM-4L
Dimensions (LxWxH)	830x600x1,319mm
FLUX production capacity	4 L
Settable solvent capacity	18L
Stirring control	speed control motor
Power requirement	3-phase, AC 200V, 1kVA

New proposal for flux supply

Benefits of using solid flux

[For solid flux transportation]

2.1 kg of solid flux is equivalent to 14 kg of liquid flux

Shipping

- 1/6 or less of the weight
- Non-dangerous goods

Domestic transportation

Overseas Export

Delivery

Customer

- Dissolve required amount in IPA
- Reduced storage space



NEW POST FLUX LT-1600Y2

Adapted to the challenges of low-temperature wave soldering using molecular analysis technology

[Features]

- Optimized viscosity ensures good fillets
- Optimized flux activity at low temperatures ensures high wettability

	Sample	LT-1600Y2
Fillet thickness		
Wettability		

Reflow soldering



MILATERA PASTE 155HF series

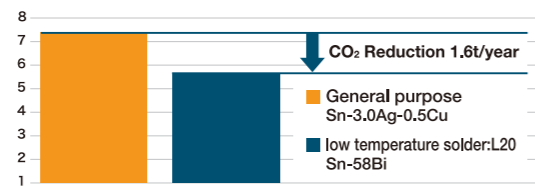
Adapted to the challenges of low-temperature reflow soldering

- [Features]
- Resolves challenges unique to low-temperature soldering with proprietary technology
 - CO₂ emissions can be reduced by 22% or more by lowering the packaging temperature
 - Product lineup suitable for various applications

MILATERA PASTE 155HF series

Solder	adaptation	L20,L23, L28,L29
	Particle size	Type4,Type5
Flux	type	155HF
	IPC classification	ROLO
viscosity		180Pa.s
Warranty		6 months

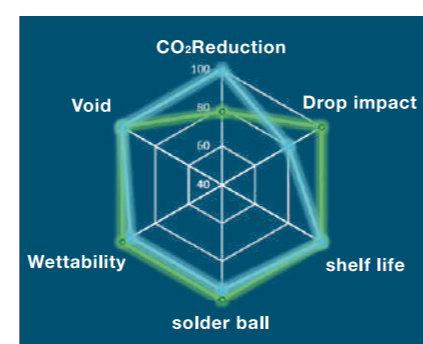
CO₂ reduction calculation



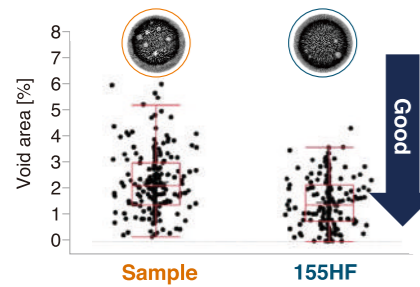
Solder type	General purpose Sn-3.0Ag-0.5Cu	low temperature solder:L20 Sn-58Bi	Reduction amount	unit	Reduction rate
Electric energy	22,848	17,760	▲5,088	kWh/year	-22.27%
CO ₂ emissions	7.27	5.65	▲1.6	t/year	-22.28%

Calculation method Assuming 1,920 hours/year operation at the standard temperature setting for each solder in one of our reflow ovens

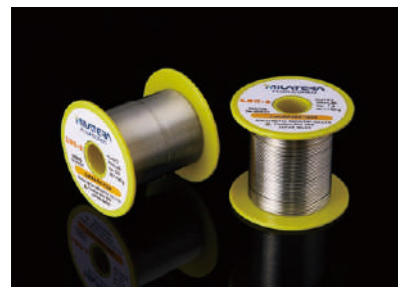
Feature Comparison Chart



void
Stencil thickness: : 0.12mm Pad size : 0.46mm
PCB surface :Cu-OSP BGA size :□15mm
BGA ball composition :SAC305 BGA ball size :Φ0.4mm



Manual soldering

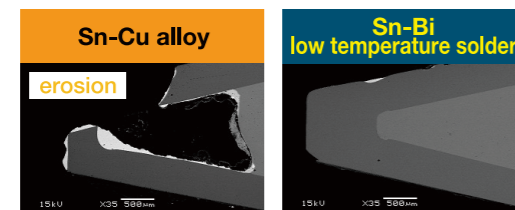


MILATERA FLUX CORED LEO-2 series

Achieved mass production supplies ahead of the rest of the industry

- [Features]
- Established mass production technology for flux-cored solder with Sn-Bi solder, which is difficult to process
 - Significantly reduced soldering iron tip wear
 - Product lineup suitable for various applications

Soldering iron tip corrosion test results

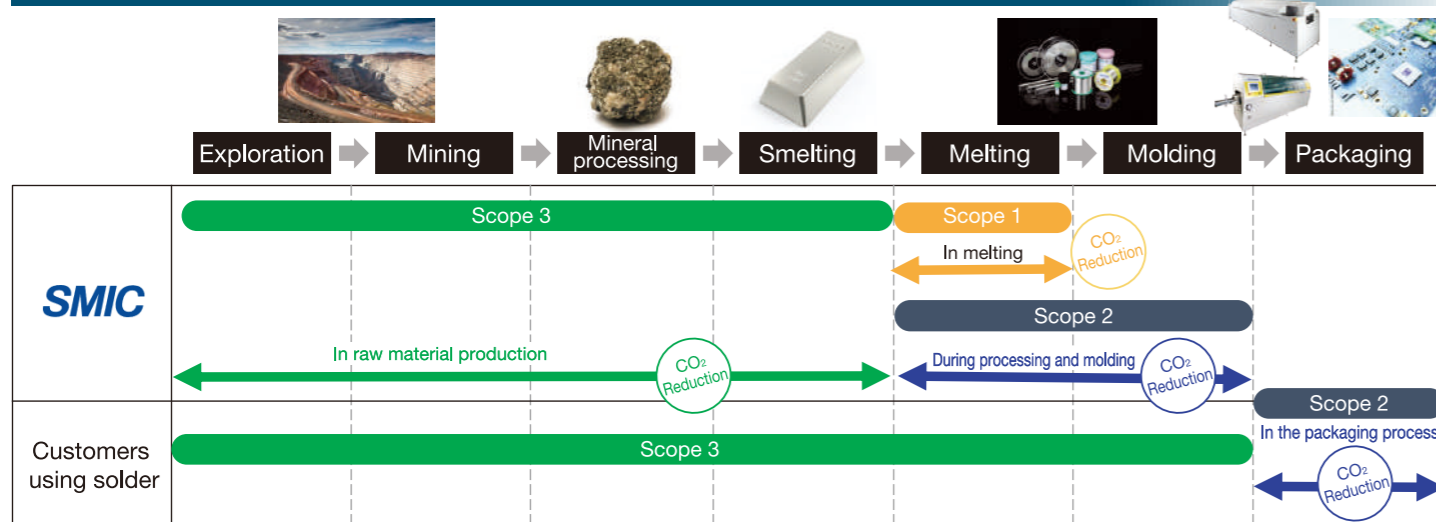


After 30,000 shots

MILATERA FLUX CORED LEO-2 series

Solder	adaptation	L20	
	type	LEO-2	LEO-2-HF
Flux	Content	2%	2%
	IPC classification	ROL1	ROL0
	Halide content	0.1% or less	0.02% or less
Tip temperature		280-380°C	

Carbon neutrality in metal mining, refining, and packaging



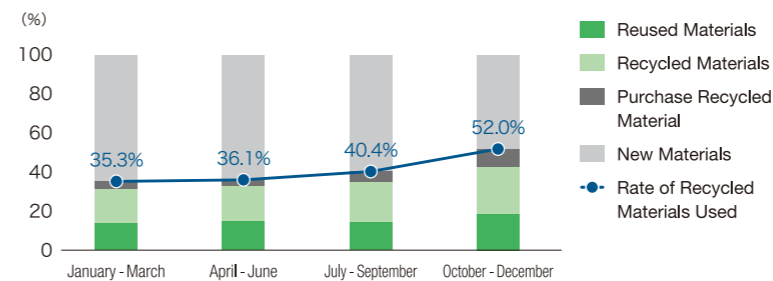
Recycling and Environmental Support

SMIC Group's Solder Recycling System

In cooperation with TAK-G, our affiliate company, we have been recycling solder for about 40 years. With the emergence of lead-free solder in the 2000s, an old era with two elements, tin and lead, into a new era with three elements, tin, silver, and copper. Today, we use more elements. Because of this development, it was required to install facilities to deal with multiple elements for recycling solder. As a result, we developed special technology that limited the emergence of hazardous materials to the absolute minimum and a solder recycling system that could reproduce high-purity solder in our own refining method. The importance of recycling solder is increasing nowadays, and the amount of recycling has doubled in the last few years, and this is expected to continue. We have assumed responsibility as a material manufacturer prior to the era when mineral recycling became popular. We will continue to actively promote investment in human resources and technological innovation toward further development of a system in which we collect the used solder products of our company and recycle them and the realization of recycling solder with multiple elements in order to achieve a sustainable society with effective utilization of limited mineral resources and the control of air pollution.



Recycled Material Usage Rates



Reduction of Harmful Chemicals

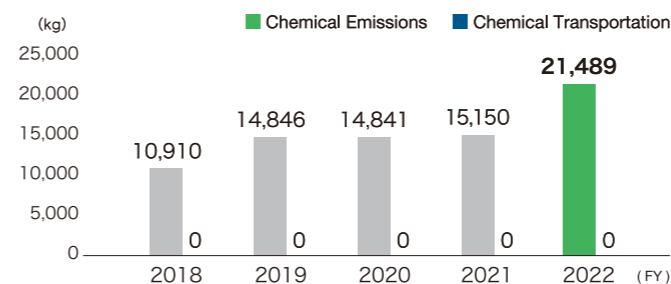
CORE PRINCIPLE

Our development, purchasing, manufacturing, and environmental departments manage chemical substances based on our environmental management system to protect our health and the environment and to realize safe and secure social life. In particular, per our plans we are implementing a reduction or prohibition of the use of chemicals that have a large environmental footprint. We also define reduction goals every year and make focused efforts.

Emissions and Movement of PRTR Law-Specified Chemicals

We comply with the PRTR law to track the amount of applicable substances we handle, emit, and transport.

Emissions and Movement of PRTR Law-Specified Chemicals



Soil and Groundwater Pollution Countermeasures

We are taking the following initiatives as soil and groundwater pollution countermeasures. We also work to prevent pollution by conducting emergency response drills, as well as risk training to prevent leaks of polluted water.

Soil	Voluntary component analysis (once per year)
Water quality and Groundwater	Final drain and groundwater inspections (chlorine residue, pH, etc. conducted daily) Component analysis and measurement of drain water and groundwater (conducted monthly)
Rainwater	Voluntary component analysis (twice per year)

AMERICA

San Jose

Chicago

US and Europe

US : San Jose, Chicago Czech Republic : Prague

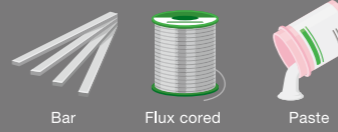


EUROPE

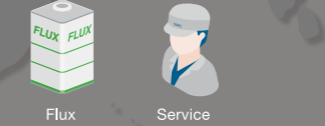
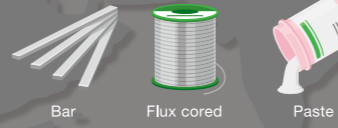
Prague

Asia

Tianjin, Shanghai, Huizhou, Hong Kong



Korea, Taiwan, Philippines, Thailand, Malaysia



JAPAN

Tianjin

Shanghai

Korea

Hong Kong

Taiwan

Huizhou

Thailand

Philippines

ASIA

Malaysia

Japan

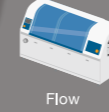
Tochigi : Moka-shi

Saitama : Soka-shi

Iwate : Ichinoseki-shi

Miyazaki : Miyazaki-shi

All Main Products



Hyogo : Nishiwaki-shi, Taka-cho

Toyama : Toyama-shi

Aichi : Seto-shi / Hyogo : Himeji-shi
Fukuoka : Onojo-shi



The Realization of a Stable Supply Chain for the SMIC Group

The SMIC Group has established a system to ensure a stable supply for its customers in Japan and around the world in order to ensure a solid foundation for a stable supply. In 2022, we faced challenges in manufacturing at our overseas group companies due to flooding and urban lockdown, but we were able to continue supplying our customers thanks to the systems we had in place. We are operating a BCP to ensure that we can fulfill our responsibility to supply our customers even in the event of unforeseen circumstances.

COMPANY PROFILE

SENJU METAL INDUSTRY CO., LTD. / SMIC GROUP

DUNS# 690663091

ESTABLISHED April 15, 1938
HEADQUARTERS ADDRESS 23 Senjuhashidocho, Adachi-ku, Tokyo 120-8555
PRESIDENT Ryoichi Suzuki

BUSINESS SCALE

REVENUE(CONSOLIDATED) ¥96,846 million (April 1, 2022 - December 31, 2022)
CAPITAL (SIMPLE) ¥400,000,000
EMPLOYEES (CONSOLIDATED) 2,204 (As of December 31, 2022)

BUSINESS PORTFOLIO

- Smelting, alloying, casting, and expansion of metals, manufacture and sale of processed goods
- Manufacture and sale of metal powders and bearings
- Manufacture and sale of solvents and adhesives for soldering
- Manufacture and sale of soldering equipment
- Manufacture and sale of fire extinguishing equipment (affiliated company business)
- Manufacture and sale of machinery related to the above businesses
- Internal dispatch business

LIST OF MAJOR AFFILIATED COMPANIES

▶ JAPAN

Industrial Analysis Service Ltd.
Senju Sprinkler Co., Ltd.
Senju Electronic Corp.
Senju Giken Co., Ltd.
Senju System Technology Co., Ltd.

▶ AMERICA

Senju America Inc.
Senju Comtek Corp.
Senju Fire Protection Corp.

▶ EUROPE (GERMANY, CZECHIA)

Senju Metal Europe GmbH
Senju Manufacturing Europe s.r.o.

▶ ASIA

Senju (Malaysia) Sdn. Bhd.
Senju Trading (M) Sdn. Bhd.
Senju (Thailand) Co., Ltd.
Senju Solder (Phils.) Inc.
Beijing Senju Fire Fighting Equipment Co., Ltd.
Senju Metal (Tianjin) Co., Ltd.

Tianjin Senju Electronics Co., Ltd.
Shanghai Senju Business Management Consulting Co., Ltd.
Senju Metal (Shanghai) Co., Ltd.
Senju Metal (Huizhou) Co., Ltd.
Senju Metal (Hong Kong) Limited
Senju Electronic Materials (Hong Kong) Co., Ltd.
Senju Electronic (Taiwan) Co., Ltd.
Senju Metal Industry Co., Ltd. Kaohsiung Branch
Senju Metal Korea Co., Ltd.

Headquarters



Segments in Japan



Tochigi Segment Matsuyama Factory



Tochigi Segment Kinugaoka Factory



Soka Segment



Chubu Segment Seto Factory



Kansai Segment Nishiwaki Factory

Affiliated Companies in Japan



Industrial Analysis Service Ltd.



Senju Sprinkler Co., Ltd.



Senju Electronic Corp.



Senju Giken Co., Ltd.



Senju System Technology Co., Ltd.



We created an official Instagram account.